

Application Note

Hyposaturation type Surface Molding Series Regulator IC

SI-3000KS series

Not Recommended for New Designs

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SANKEN ELECTRIC CO., LTD.

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1. General Information

The SI-3000KS is a series regulator IC using a hyposaturation type PNP bipolar transistor in the power section and it can be used with the low difference of input/output voltages. It is provided with an ON / OFF terminal which operates in Active High mode and the current consumption of circuits at OFF time is zero. It is a regulator which can use low ESR capacitors such as ceramic capacitors for the output capacitor at the voltage of 17V.

● 1-1 Features

- Output current 1A
Output current is 1A at maximum with the outline of SOP8.
- Hyposaturation ($V_{dif} = 0.6V_{max} / I_o = 1A$)
It can be designed with low difference of input/output voltages.
- ON/OFF function
The ON/OFF terminal which can be directly controlled by TTL logic signals is provided.
- Low current consumption
Current consumption of circuits at OFF time is zero.
Dark currents at no load are 350 μ A at maximum.
- Built-in Overcurrent protection / Thermal shutdown
The current limiting type overcurrent protection and Thermal shutdown circuits are built-in.
(Automatic restoration type)

● 1-2 Application

For on-board local power supplies, power supplies for OA equipment, stabilization of secondary output voltage of regulator and power supply for communication equipment

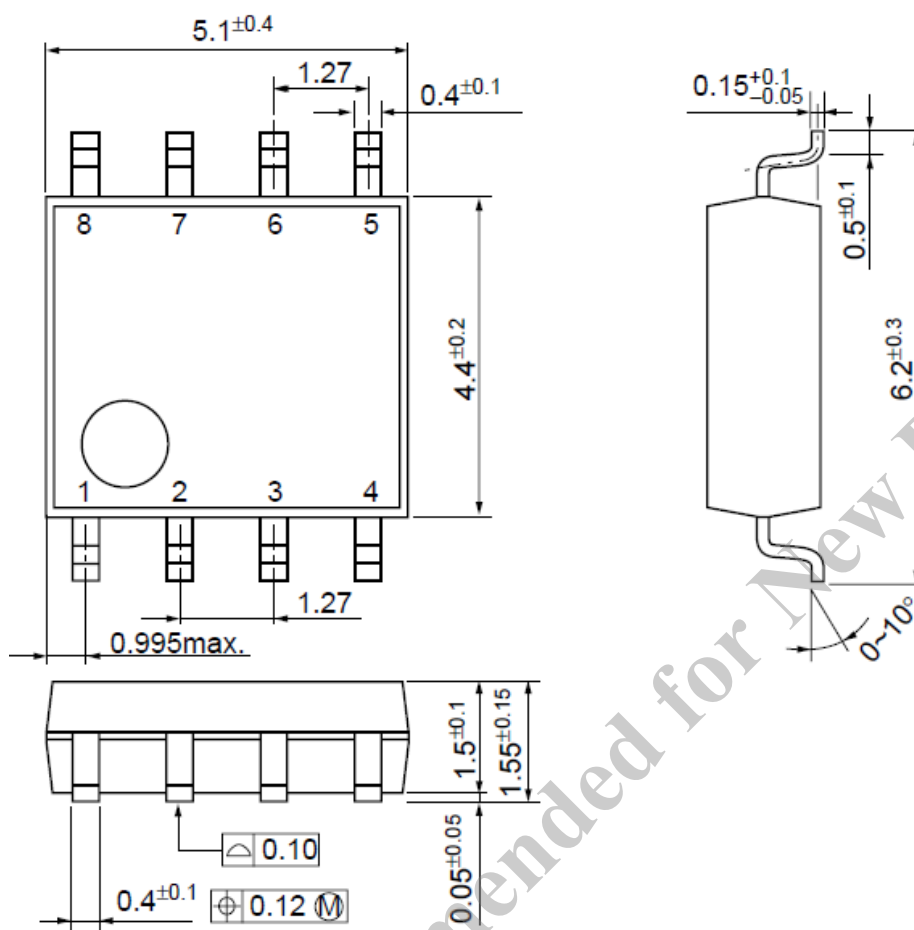
● 1-3 Type

- Type: Semiconductor integrated circuits (monolithic IC)
- Structure: Resin molding type (transfer molding)

2. Specification

Unit: mm

● 2-1 Package Information



Pin assignment

1. V_c
2. V_{IN}
3. V_o
4. Sense (ADJ for SI-3012KS)
5. GND
6. GND
7. GND
8. GND

Resin sealed type

Non-combustibility: UL standards 94V-0

Product mass: about 0.1 g

● 2-2 Ratings

2-2-1 Absolute Maximum Ratings

Ta = 25°C

Parameter	Symbol	Ratings	Unit
DC Input Voltage	V _{IN} ^{*1}	17	V
Output Control Terminal Voltage	V _C	V _{IN}	V
DC Output Current	I _O ^{*1}	1.0	A
Power Dissipation	P _D ^{*1, *2}	0.76	W
Junction Temperature	T _J	-40 to +125	°C
Storage Temperature	T _{stg}	-40 to +125	°C
Thermal Resistance (Junction to Ambient Air)	θ _{J-a}	130	°C/W
Thermal resistance (Junction to Lead (pin 7))	θ _{J-L}	22	°C/W

*1: V_{IN} (max) and I_O (max) are restricted by the relation P_D = (V_{IN} - V_O) × I_O. Please calculate these values referring to the Copper laminate area vs. Power dissipation data as shown hereinafter.

*2: When mounted on a glass epoxy board of 1600mm² (copper laminate are 2%).

2-2-2 Recommended Conditions

Parameter	Symbol	Ratings			Unit
		^{*2} SI-3012KS ^{*1}	^{*2} SI-3025KS ^{*1}	^{*2} SI-3033KS ^{*1}	
Input Voltage	V _{IN}	2.4 - 6.0	- 6	- 6	V
Output Current	I _O	0 - 1.0			A
Operational Ambient Temperature	Top	-30 - 85			°C
Junction Temperature in Operation	T _J	-20 - 100			°C

*1: Because of the relation of P_D = (V_{IN} - V_O) × I_O, V_{IN} (max.) and I_O (max.) may be restricted subject to conditions of use. For each value, refer to the data of copper foil area - permissible loss for calculation.

*2: It should be V_O + input/output voltage difference.

2-2-3 Electrical Characteristics

Ta = 25°C

Parameter	Symbol	Ratings									Unit
		SI-3012KS (variable type)			SI-3025KS			SI-3033KS			
		min.	typ.	max.	min.	typ.	max.	min.	typ.	max.	
Input Voltage	V _{IN}	2.4			1			1			V
Output Voltage (Reference voltage V _{ADJ} for SI-3012KS)	V _O (V _{ADJ})	1.24	1.28	1.32	2.45	2.50	2.55	3.234	3.300	3.366	V
	Conditions	V _{IN} =3.3V, I _O =10mA			V _{IN} =3.3V, I _O =10mA			V _{IN} =5V, I _O =10mA			
Dropout Voltage	V _{DIF}			0.3			0.4			0.4	V
	Conditions	I _O =0.5A (V _O =2.5V)			I _O =0.5A			I _O =0.5A			
				0.6			0.6			0.6	
Line Regulation	ΔV _{LINE}			10			10			15	mV
	Conditions	V _{IN} =3.3 to 8V, I _O =10mA (V _O =2.5V)			V _{IN} =3.3 to 8V, I _O =10mA			V _{IN} =5 to 10V, I _O =10mA			
Load Regulation	ΔV _{LOAD}			40			40			50	mV
	Conditions	V _{IN} =3.3V, I _O =0 to 1A (V _O =2.5V)			V _{IN} =3.3V, I _O =0 to 1A			V _{IN} =5V, I _O =0 to 1A			
Quiescent Circuit Current	I _q			350			350			350	μA
	Conditions	V _{IN} =3.3V, I _O =0A, V _C =2V, R ₂ =24kΩ			V _{IN} =3.3V, I _O =0A, V _C =2V			V _{IN} =5V, I _O =0A, V _C =2V			
Circuit Current at Output OFF	I _q (OFF)			1			1			1	μA
	Conditions	V _{IN} =3.3V, V _C =0V			V _{IN} =3.3V, V _C =0V			V _{IN} =5V, V _C =0V			
Temperature Coefficient of Output Voltage	ΔV _O /ΔT _a			±0.3			±0.3			±0.3	mV/°C
	Conditions	T _J =0 to 100°C (V _O =2.5V)			T _J =0 to 100°C			T _J =0 to 100°C			
Ripple Rejection	R _{REJ}			55			55			55	dB
	Conditions	V _{IN} =3.3V, f=100 to 120Hz (V _O =2.5V)			V _{IN} =3.3V, f=100 to 120Hz			V _{IN} =5V, f=100 to 120Hz			
Overcurrent Protection Starting Current ²	I _{S1}	1.2			1.2			1.2			A
	Conditions	V _{IN} =3.3V (V _O =2.5V)			V _{IN} =3.3V			V _{IN} =5V			
V _C Terminal	Control Voltage (Output ON) ³	V _C , I _H	2.0		2.0			2.0			V
	Control Voltage (Output OFF)	V _C , I _L			0.8			0.8		0.8	
	Control Current (Output ON)	I _C , I _H			40			40		40	μA
	Conditions	V _C =2V									
	Control Current (Output OFF)	I _C , I _L	-5	0		-5	0		-5	0	
Conditions	V _C =0V										

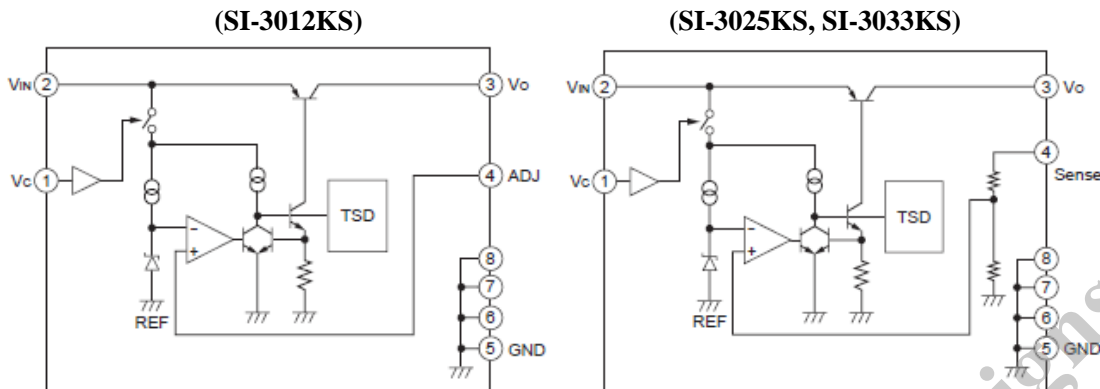
*1: Refer to the Dropout Voltage parameter.

*2: The I_{S1} is specified at the 5% drop point of output voltage V_O on the condition that V_{IN} = V_O +1V, and I_O = 10mA.

*3: Output is OFF when the output control terminal V_C is open. Each input level is equivalent to LS-TTL level. Therefore, the device can be driven directly by LS-TTLs.

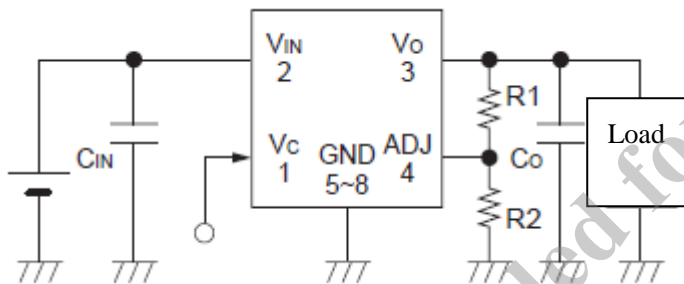
● **2-3 Circuit Diagram**

2-3-1 Block Diagram



2-3-2 Typical Connection Diagram

(SI-3012KS)



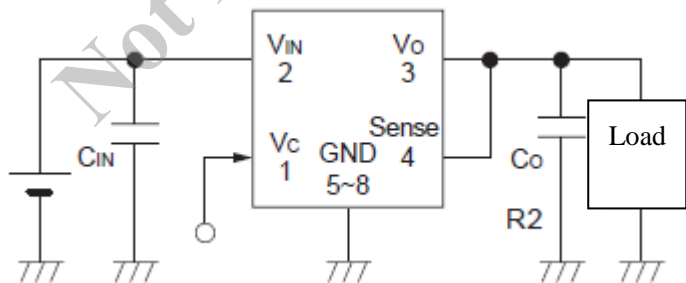
R1, R2: resistors for setting output voltages

Output voltages can be adjusted by connecting R1 and R2 as shown in the above figure.

R2: 24kΩ is recommended.

$$R1 = (V_o - V_{ADJ}) / (V_{ADJ} / R2)$$

(SI-3025KS, SI-3033KS)



Low ESR capacitors such as ceramic capacitors are used for the output capacitor to compose a circuit in SI-3000KS. In the case that electrolytic capacitors are used, they may oscillate because of increase of ESR.

Therefore the use of electrolytic capacitors is not recommendable.

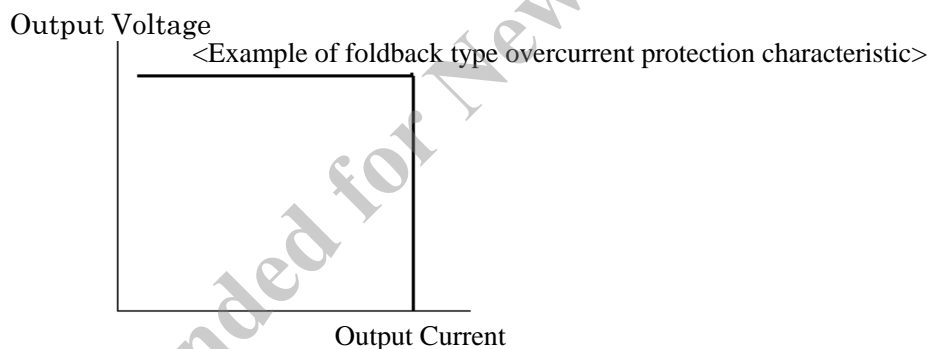
3. Operational Description

● 3-1 Voltage Control

In the SI-3000KS series, the driving circuit is controlled by comparing the reference voltage with the ADJ terminal voltage (voltage divided by V_o detection resistor in fixed output products) to stabilize the output voltage by varying the voltage between the emitter and collector of a main PNP power transistor. The product of voltage between emitter and collector and the output current at this moment is consumed as heat.

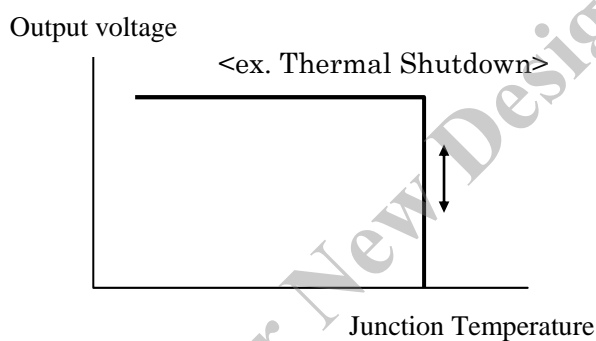
● 3-2 Overcurrent Protection

The current limiting type overcurrent protection function is provided in the SI-3012KD and the SI-3033KD. In the case of the series regulator, as the output voltage drops subject to the overcurrent protection, the difference of input/output voltages increases to cause significant heating. Special care should be taken for the current limiting type overcurrent protection, since large current flows continuously.



● 3-3 Thermal Shutdown

This IC is provided with the overheat protection circuit which detects the semiconductor junction temperature of the IC to limit the driving current, when the junction temperature exceeds the set value (around 150°C). Since the minimum operating temperature of the overheat protection circuit is 130°C, the thermal design of $T_j < 125^\circ\text{C}$ is required. Since the overheat protection has no hysteresis, as soon as the overload state is released and T_j falls below the set temperature, the normal operation is automatically restored. When the overheat protection function is operated in the overload state, the output voltage falls, but at the same time the output current is decreased and in the consequence, overheat protection operation and automatic restoration are repeated in a short interval, resulting eventually in the waveforms of output voltage oscillation.



*Note for thermal shutdown characteristic

This circuit protects the IC against overheat resulting from the instantaneous short circuit, but it should be noted that this function does not assure the operation including reliability in the state that overheat continues due to long time short circuit.

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4. Cautions

● 4-1 External Components

4-1-1 Input Capacitor C_{IN}

The input capacitor is required to eliminate noise and stabilize the operation and values of 0.47μF - 22μF are recommended. Any of ceramic capacitors or electrolytic ones may be used for the input capacitor.

4-1-2 Output Capacitor C_O

In the output capacitor C_O, larger capacitance than the recommended value is required for phase compensation. Equivalent series resistance values (ESR) of capacitors are limited, and depending on products, therefore the type of recommended capacitors is limited.

- SI-3012KS, SI-3025KS, SI3033KS Recommendation: ESR < 0.2Ω

It is recommended to use ceramic capacitors or functional polymer capacitors. If electrolytic capacitors having large ESR are used, the phase margin is decreased to cause the possible oscillation of output voltage. Even if oscillation does not occur at low temperature, ESR is increased to cause oscillation. Therefore the use of electrolytic capacitors is not recommendable.

4-1-3 Reverse bias protection diode D1

In the case of falling-down of the input voltage, it is recommended to insert a protection diode D1 against the reverse bias between input and output. However, in the case of setting the V_{out} < 3.3V or lower, D1 is not required including the case of reverse bias. In order to select a suitable D1, it should be taken into consideration that the diode has adequate forward current withstand voltage against the instantaneous discharge of energy stored in C_{out}.

The permissible value of the forward current per unit time of diode is specified in I_{FSM} (A) and in the case of our diode, it is specified at 50Hz half wave (10ms), but it should be noted that different companies may specify different times. The selection of diode should be made by converting the specified time into the actual discharging time so as to meet the required I_{FSM} (A). The discharging time of C_O is normally shorter than 1ms, but it is recommended to do the conversion with 1ms in consideration of margin.

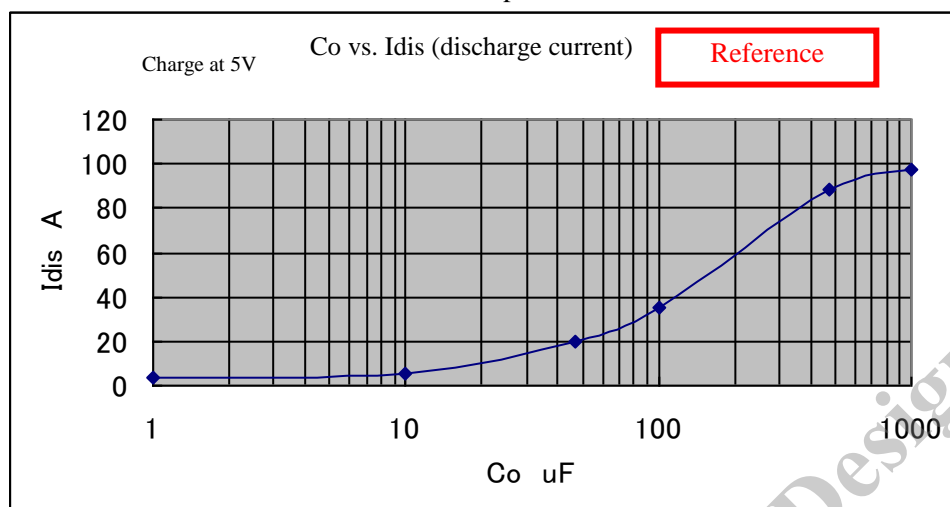
For conversion into I_{FSM}, calculation should be made by using the equations (1) and (2).

$$\left(\frac{I_{FSM}}{\sqrt{2}}\right)^2 * t1 = X \quad \text{--- (1) As for } I_{FSM}, \text{ please refer to the catalog of each company.}$$

t1 = specified time in catalog of each company

$$\text{Converted IFSM} = \sqrt{\frac{2 * X}{t2}} \quad \text{--- (2)} \quad t2: \text{ converted time (discharging time of Co)}$$

<Graph 1>



On the assumption of $C_{out} = 470\mu\text{F}$, I_{FSM} of around 90A or more (in 1ms time period) is required and according to our specifications of D_i , I_{FSM} is specified for 10ms, therefore the D_i of 30A has the tolerated dose of 94.8A (in 1ms) to prove that it is usable.

● 4-2 Pattern Design Notes

4-2-1 Input / Output Capacitor

The input capacitor C1 and the output capacitor C2 should be connected to the IC as close as possible. If the rectifying capacitor for AC rectifier circuit is on the input side, it can be used as an input capacitor. However, if it is not close to the IC, the input capacitor should be connected in addition to the rectifying capacitor.

4-2-2 ADJ Terminal (Output Voltage Set-up for SI-3012KS)

The ADJ terminal is a feedback detection terminal for controlling the output voltage.

The output voltage set-up is achieved by connecting R1 and R2.

SI-3012KS: it should be set in a manner that I_{ADJ} is around $50\mu\text{A}$.

R1, R2 and output voltage can be obtained by the following equations:

$$I_{ADJ} = V_{ADJ} / R2 \quad \left[*V_{ADJ} = 1.28\text{V} \pm 3\% \text{ (SI-3012KS, } R2 = 24\text{k}\Omega \text{ recommended)} \right]$$

$$R1 = (V_o - V_{ADJ}) / I_{ADJ} \quad R2 = V_{ADJ} / I_{ADJ}$$

$$V_{out} = R1 \times (V_{ADJ} / R2) + V_{ADJ}$$

5. Applications

● 5-1 Output ON/OFF Control

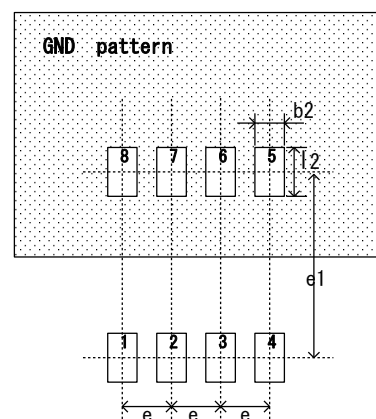
The ON/OFF control of output can be made by directly applying voltage to No. 1 Vc terminal. When the Vc terminal is open, the operation is in OFF. The Vc terminal is in OFF below 0.8V and in ON at above 2V.

● 5-2 Thermal Design

Calculation of heat dissipation

Heat generation of the surface mounting IC is generally dependent on size, material and copper foil area of the mounted printed circuit board. The inner frame stage on which the monolithic IC is mounted is directly connected to the GND terminal (5 – 8 pins). Therefore, the heat dissipation effect is increased by enlarging the copper foil area connected to the GND terminal. As shown in Fig. 1, it is recommended to design in a manner that the insulation film is opened only in the solder pattern of Nos. 5, 6, 7 and 8 pins connected to the GND pattern widely arranged.

As the junction temperature T_j (MAX) is a product-specific value, it must be observed strictly. For this purpose, heat sink design (thermal resistance of board) which is appropriate for P_d (MAX) and T_a MAX is required. This is graphically shown in the heat derating curve for easy understanding. The heat dissipation design is done in the following procedure.



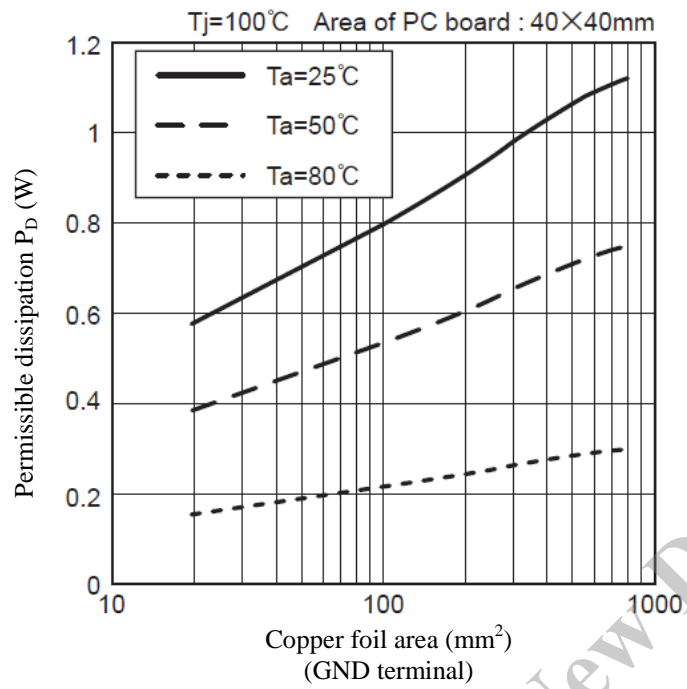
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- 1) The highest ambient temperature in the set T_a MAX is obtained.
- 2) The maximum loss P_d MAX which varies the input/output conditions is obtained.

$$P_d = (V_{IN} - V_{out}) \times I_{out}$$

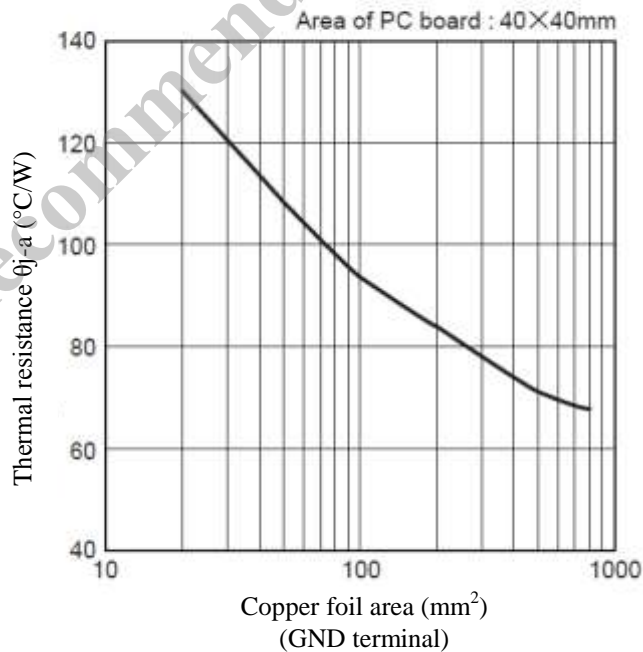
- 3) The area of copper foil is determined from the graph of copper foil area vs. permissible dissipation below shown.

Copper foil area vs. Permissible dissipation



For reference information, the graph of copper foil area vs. thermal resistance between junction temperature and ambient temperature θ_{j-a} that is in the single side copper foil board FR - 4 are shown below.

Copper foil area vs. thermal resistance θ_{j-a}

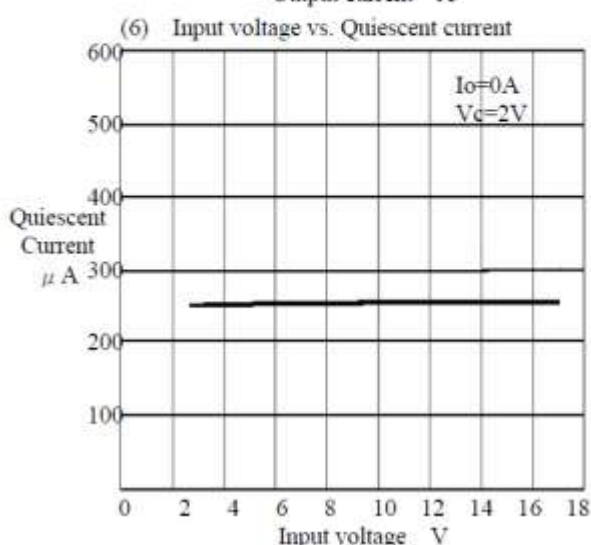
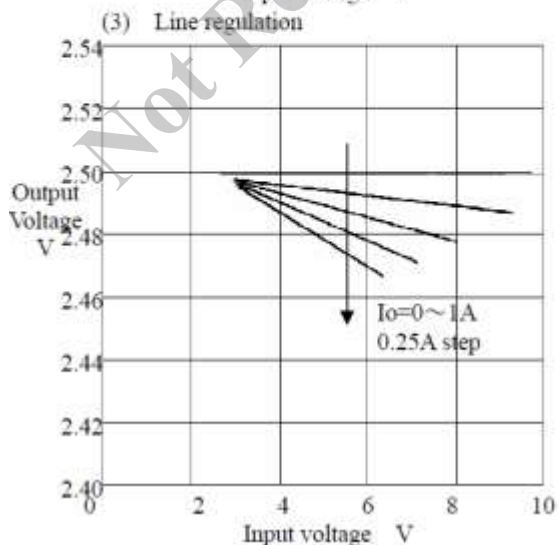
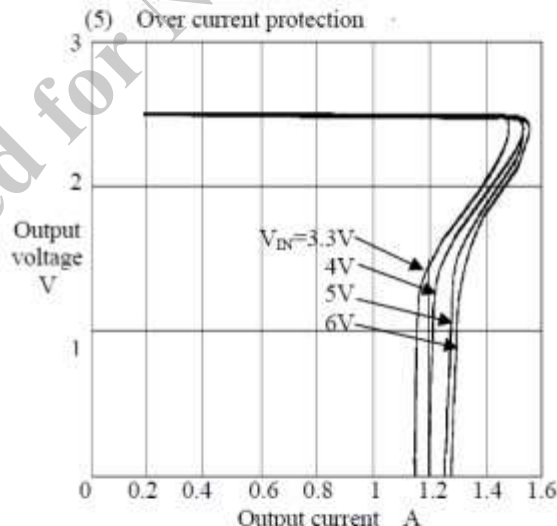
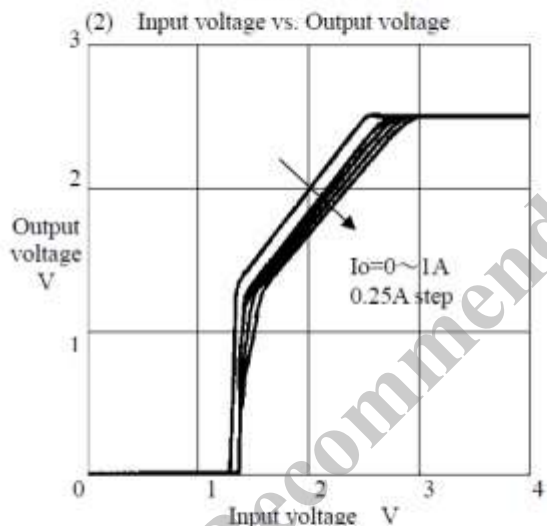
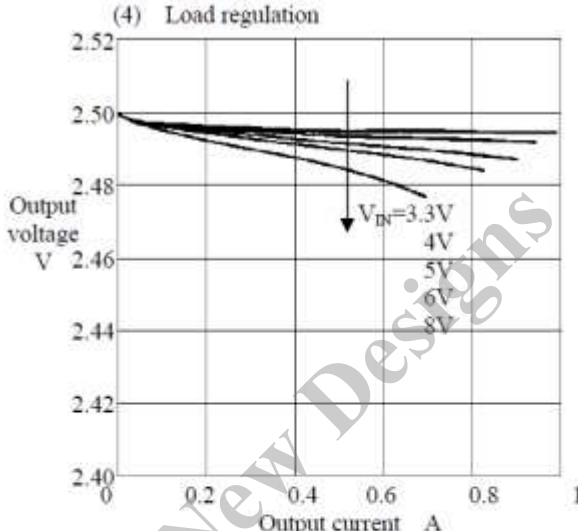
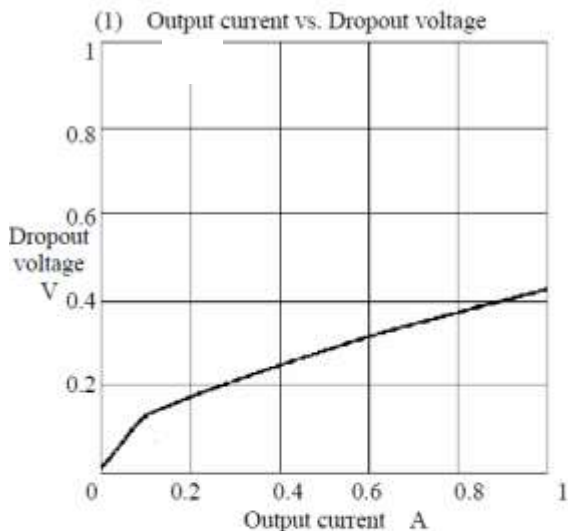


6. Typical Characteristics

- SI-3012KS

(Ta = 25°C)

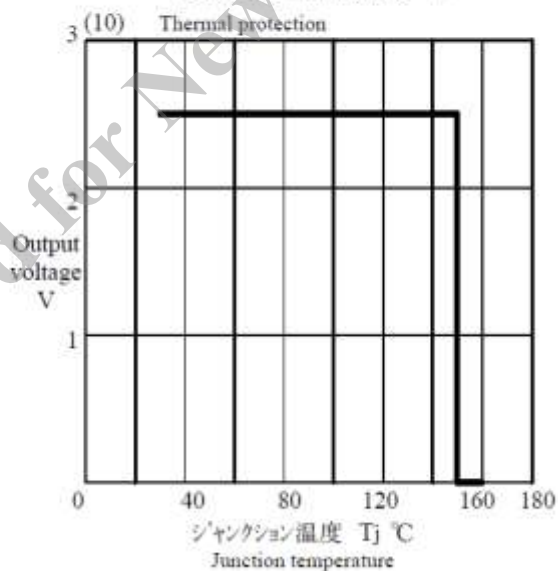
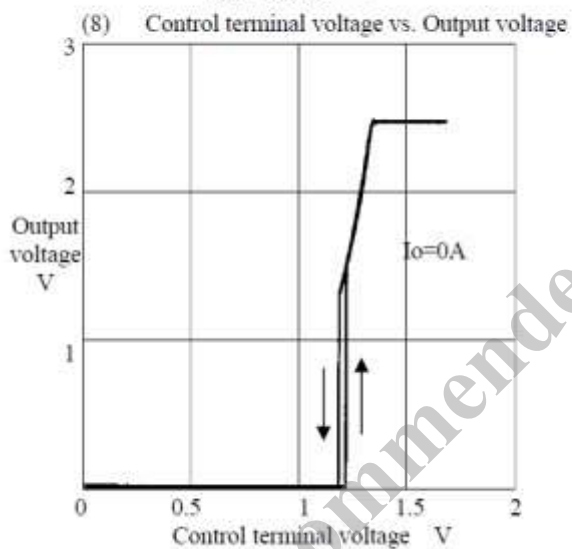
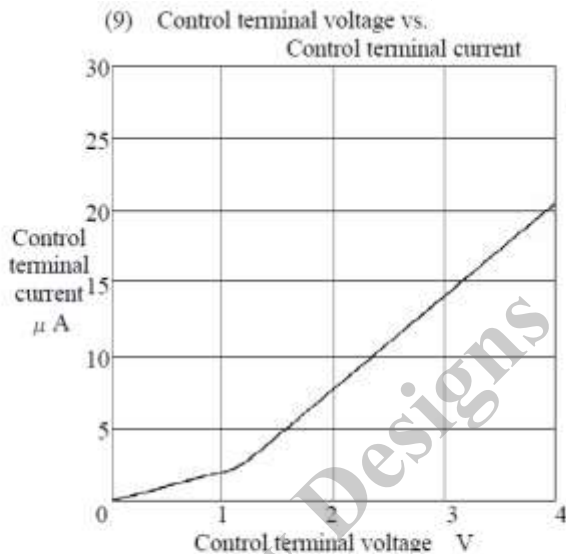
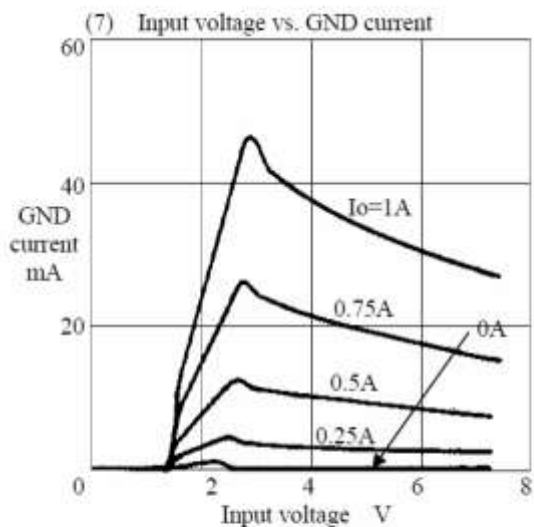
*Set Vout = 2.5V (R2 = 24kΩ)



- SI-3012KS

(Ta = 25°C)

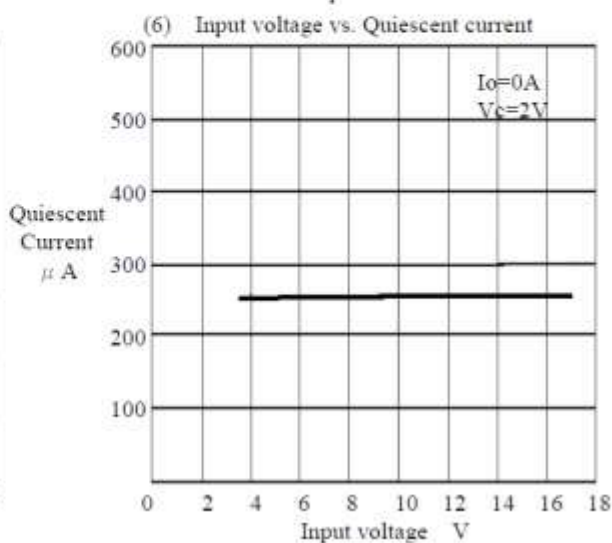
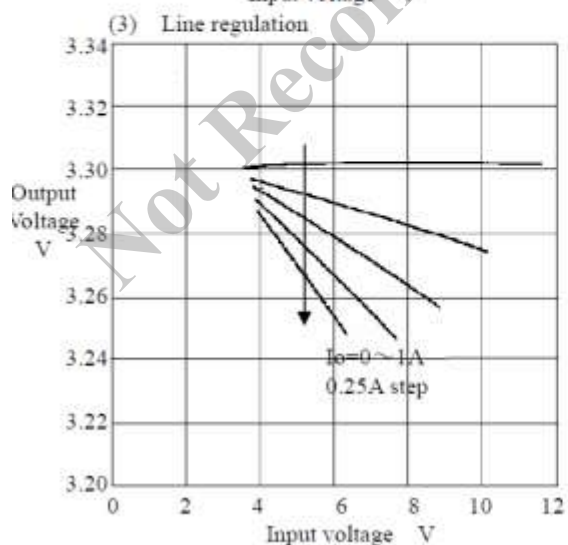
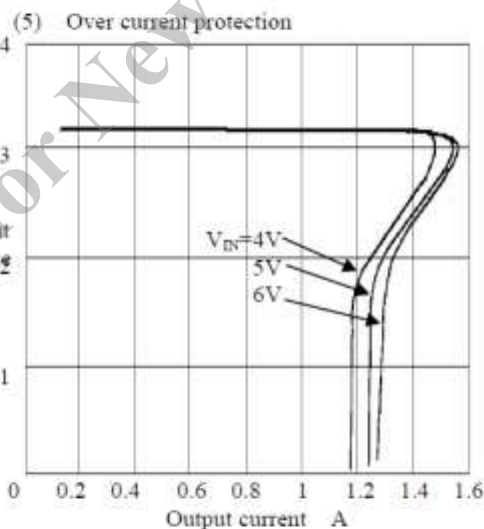
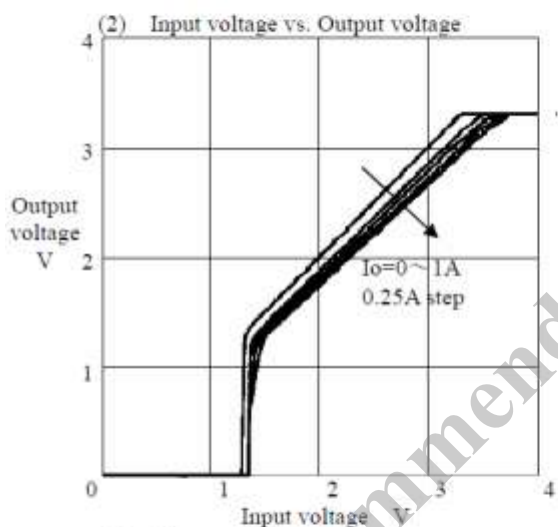
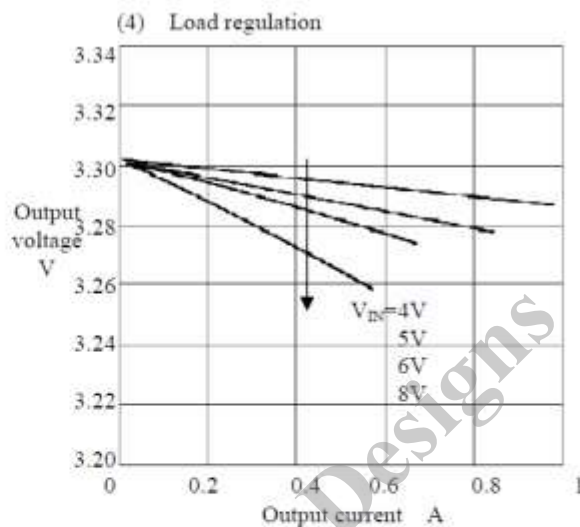
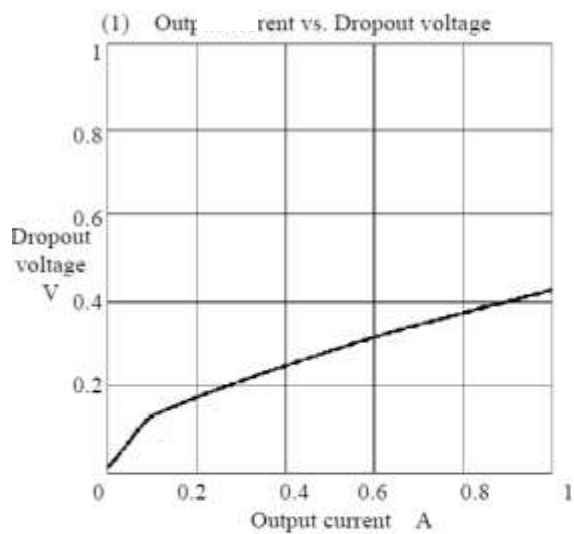
*Set Vout = 2.5V (R2 = 24kΩ)



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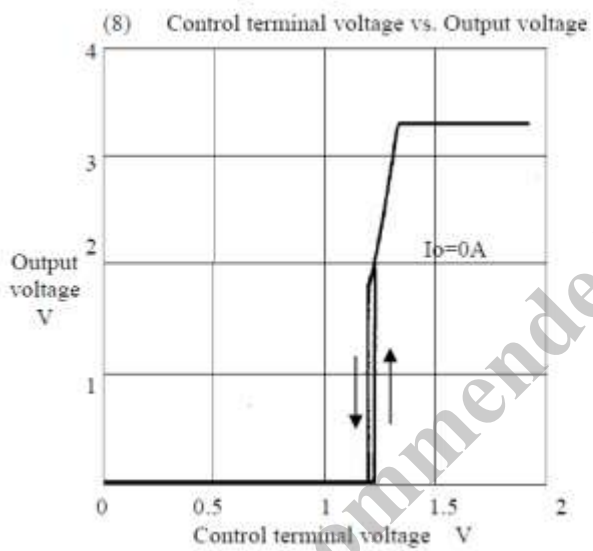
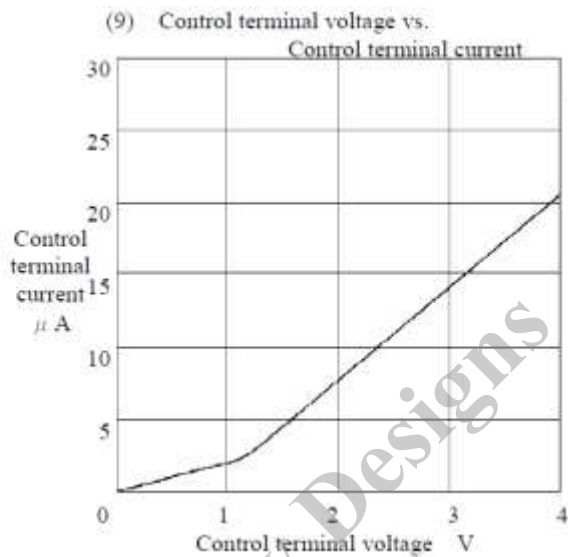
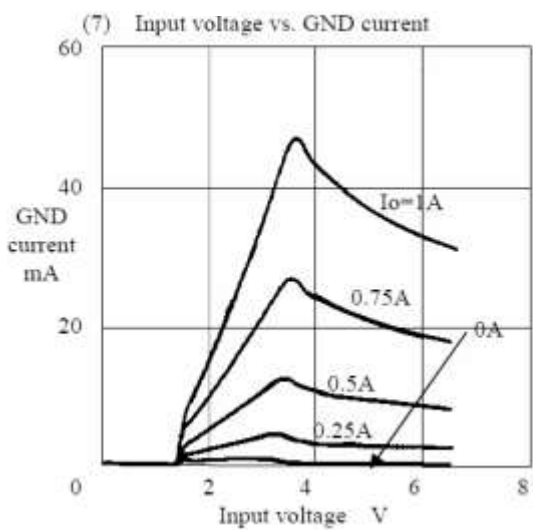
- SI-3033KS

(Ta = 25°C)



- SI-3033KS

($T_a = 25^\circ\text{C}$)



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